

INTERNATIONAL MICRO INDUSTRIES (IMI) IS ITAR REGISTERED.

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Cherry Hill, NJ, 30 July 2009 — International Micro Industries, Inc. (IMI) is now ITAR (International Traffic in Arms Regulations) registered for its Cherry Hill, New Jersey manufacturing facility. ITAR regulates the manufacture, export, and transfer of defense-related articles, information, and services and is under direct oversight of the US Department of State. ITAR registration is a requirement for participation in many defense-related manufacturing and development programs. Chris Angelucci, IMI's President, noted, "IMI is committed to providing the highest quality wafer bumping and wafer level processing services in the semiconductor industry, enabling our customers to remain on the leading edge of advanced packaging and sensor design. We work with a significant number of defense-related companies because IMI caters to extreme hi-reliability specifications, fine pitch, void-free and exotic material needs for the most demanding D.O.D, aerospace, and medical applications. IMI's ability to provide end-to-end, in-house development and production enhances IP security while enabling the quick-turnaround necessary for defense-related work. Being ITAR registered positions us perfectly to support these programs."

About International Micro Industries, Inc.:

Founded in 1971, IMI (<http://www.imi-corp.com>) is a provider of wafer bumping and wafer level processing (WLP) contract services to EMS customers and end-users in the advanced packaging, MEMS and advanced sensor markets. A MIL-qualified domestic resource, IMI's Cherry Hill, NJ manufacturing facility is structured to meet the technical and logistical challenges associated with defense-related programs. The firm provides scalable wafer bumping and wafer level processing services from prototyping of new designs through high-volume sustained production and turn-key technology licensing agreements for a wide array of DOD, Aerospace, Automotive, Advanced Sensor, Medical Implantable, Medical Disposable, Communication and RFID businesses. IMI's fine pitch electroplated bumps and structures in Au, Au/Sn Alloy, Sn/Pb Alloy, In, Cu, Ni, & Ag in heights from 1 to 150 microns, with aspect ratios of better than 3:1 provide customers with the process latitude that enables them to stay responsive to their program requirements while remaining ultra-competitive... even in low-volume or short-run programs. IMI's thick-film photoresist and proprietary high aspect ratio plating technology makes tighter pitches, higher performance and smaller form factors possible, enabling customers to push the envelope of advanced packaging and sensor design.

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